

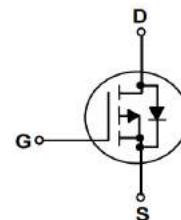
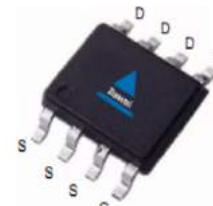


Features

- P-Channel
- Very low on-resistance $R_{DS(ON)}$
- Reliable and Rugged
- Avalanche Rated
- 100% EAS Tested

V_{DS}	-30	V
$R_{DS(on),TYP} @ V_{GS}=-10\text{ V}$	8	mΩ
$R_{DS(on),TYP} @ V_{GS}=-4.5\text{ V}$	12	mΩ
I_D	-12	A

SOP-8



Part ID	Package Type	Marking	Packing
ZT090P03S	SOP-8	ZT090P03S	4000pcs/reel

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
Common Ratings ($T_c=25^\circ\text{C}$ Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	± 25	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-30	V
T_J	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c=25^\circ\text{C}$	-54
			A
Mounted on Large Heat Sink			
I_D	Drain Current-Continuous	$T_c=25^\circ\text{C}$	-12
		$T_c=100^\circ\text{C}$	-8
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	3.6
		$T_c=100^\circ\text{C}$	1.4
$R_{\theta JC}$	Thermal Resistance-Junction to Case	35.7	°C/W
Drain-Source Avalanche Ratings			
EAS	Avalanche Energy, Single Pulsed (Note 2)	225	mJ



Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J=25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 25\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.5	-2.0	V
$R_{\text{DS}(\text{on})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-12\text{A}$	--	8	10.5	$\text{m}\Omega$
$R_{\text{DS}(\text{on})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-7\text{A}$	--	12	16	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-20\text{A}$	--	60	--	S

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	1780	--	pF
C_{oss}	Output Capacitance		--	240	--	pF
C_{rss}	Reverse Transfer Capacitance		--	205	--	pF
R_g	Gate Resistance	$f=1\text{MHz}$	--	2.5	--	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-15\text{A}, V_{\text{GS}}=-10\text{V}$	--	46	--	nC
Q_{gs}	Gate-Source Charge		--	1.0	--	nC
Q_{gd}	Gate-Drain Charge		--	1.4	--	nC

Switching Characteristics

$T_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=-15\text{V}, R_L=1\Omega, R_G=3\Omega, V_{\text{GS}}=-10\text{V}$	--	8	--	ns
T_r	Turn-on Rise Time		--	27	--	ns
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		--	68	--	ns
T_f	Turn-Off Fall Time		--	39	--	ns

Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

I_{SD}	Source-Drain Current (Body Diode)		--	--	-12	A
V_{SD}	Forward on voltage ^(Note 3)	$I_{\text{S}}=-20\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.2	V
T_{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_{\text{SD}}=-4\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	--	13.5	--	ns
Q_{rr}	Reverse Recovery Charge		--	3.7	--	nC

Notes :

1.Repetitive Rating: Pulse width limited by maximum junction temperature.

2.E_{AS} condition: $T_J=25^\circ\text{C}, V_{\text{DD}}=-30\text{V}, V_{\text{G}}=-10\text{V}, R_g=25\Omega, L=0.5\text{mH}$.

3.Repetitive Rating: Pulse width limited by maximum junction temperature.



Typical Electrical And Thermal Characteristics (Curves)

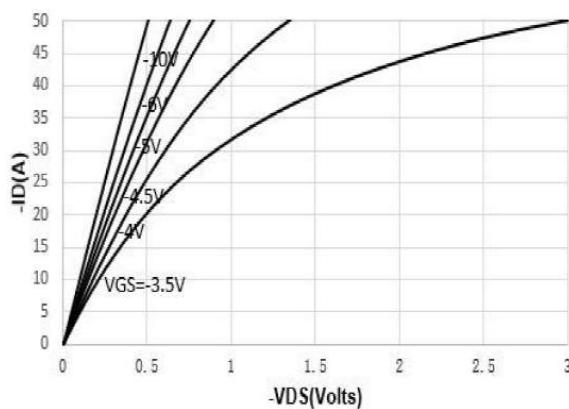


Figure 1. On-Region Characteristics

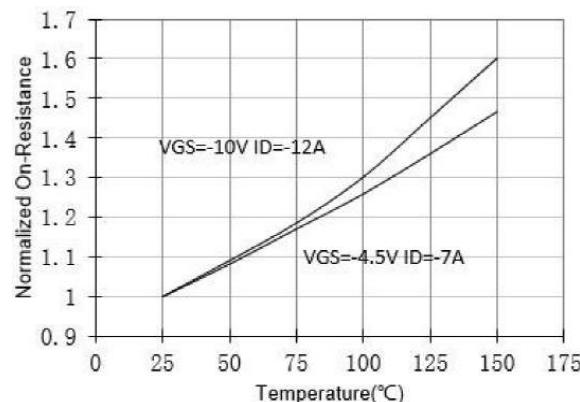


Figure 4. On-Resistance vs. Junction Temperature

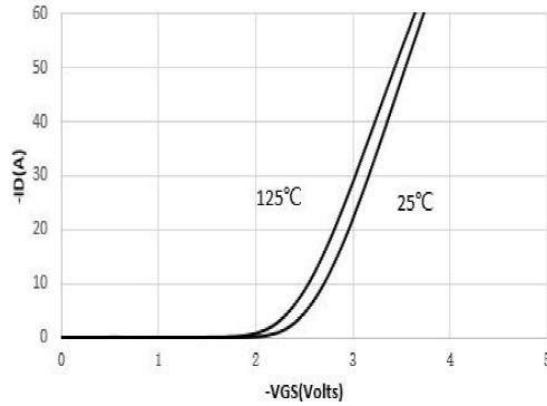


Figure 2. Transfer Characteristics

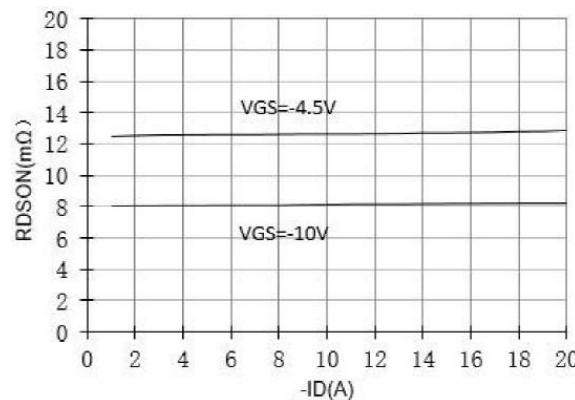


Figure 5. On-Resistance vs. Drain Current and Gate Voltage

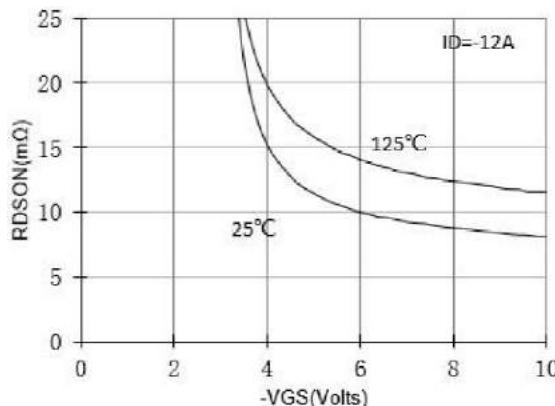


Figure 3. On-Resistance vs. Gate-Source Voltage

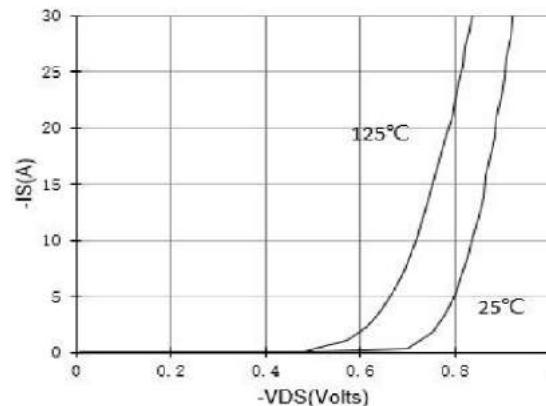


Figure 6. Body-Diode Characteristics

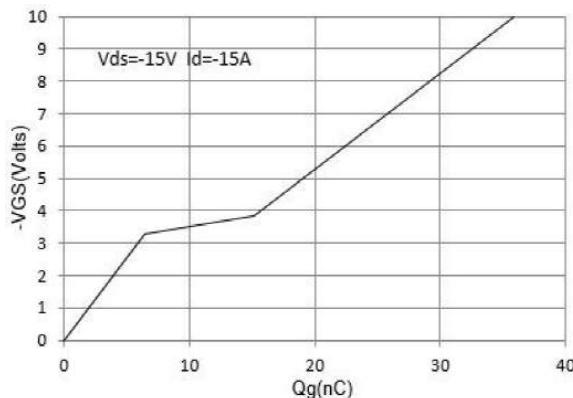


Figure 7 Gate-Charge Characteristics

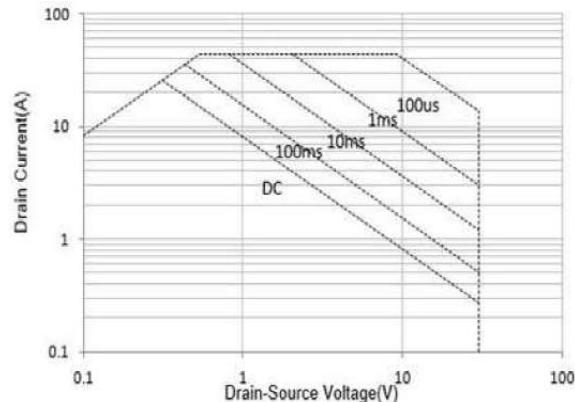


Figure 9. Maximum Forward Biased Safe Operating Area

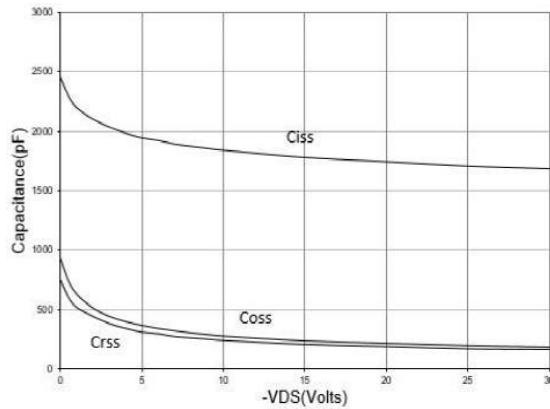


Figure 8 Capacitance Characteristics

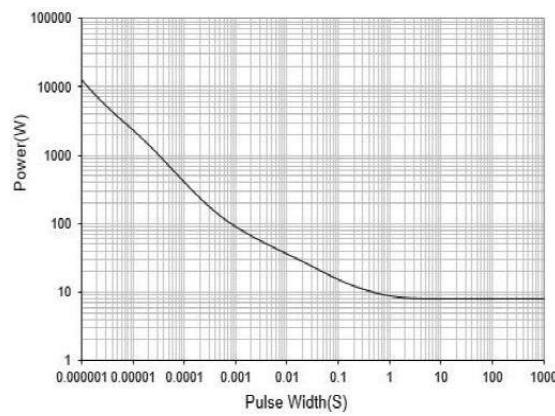


Figure 10. Single Pulse Power Rating Junction-to-Ambient

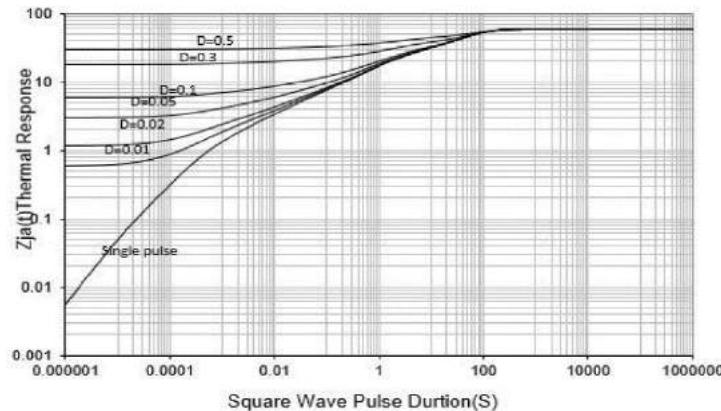
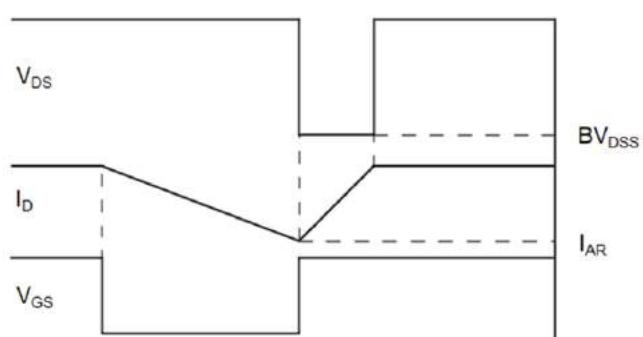
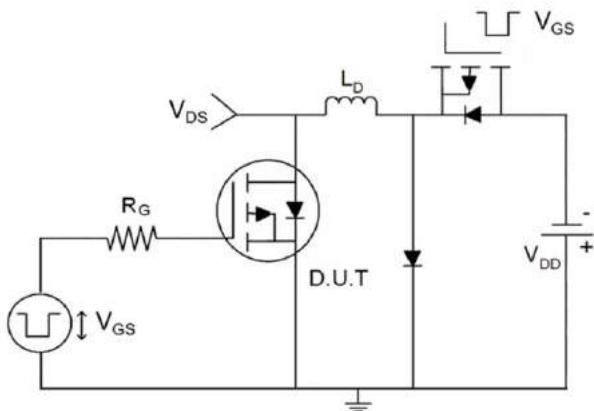


Figure 11. Normalized Maximum Transient Thermal Impedance

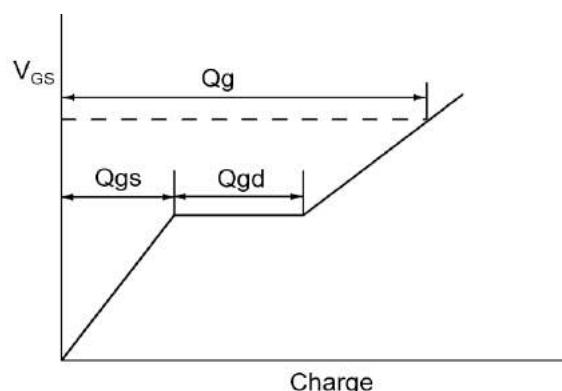
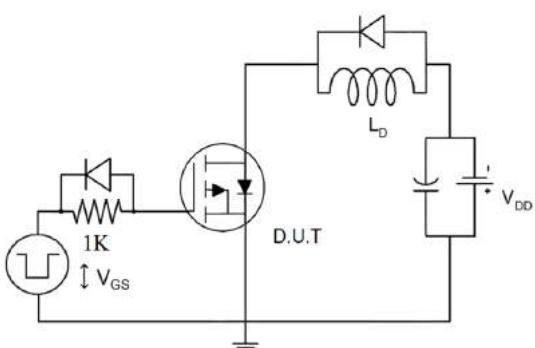


Test Circuit

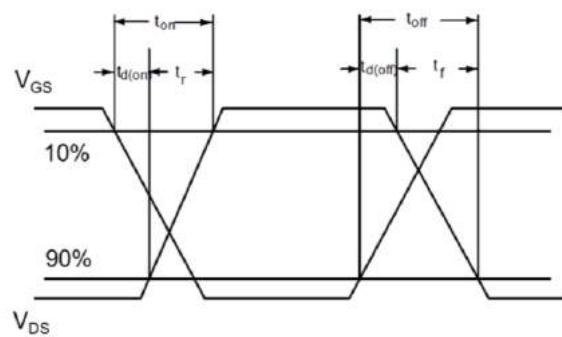
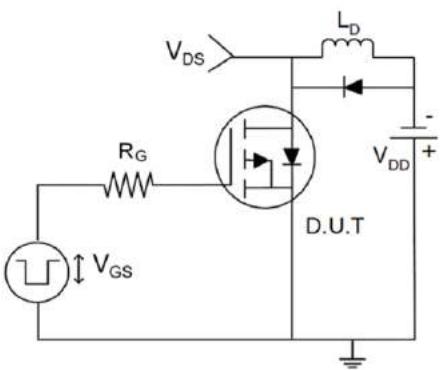
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit

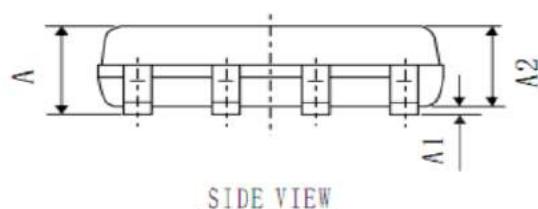
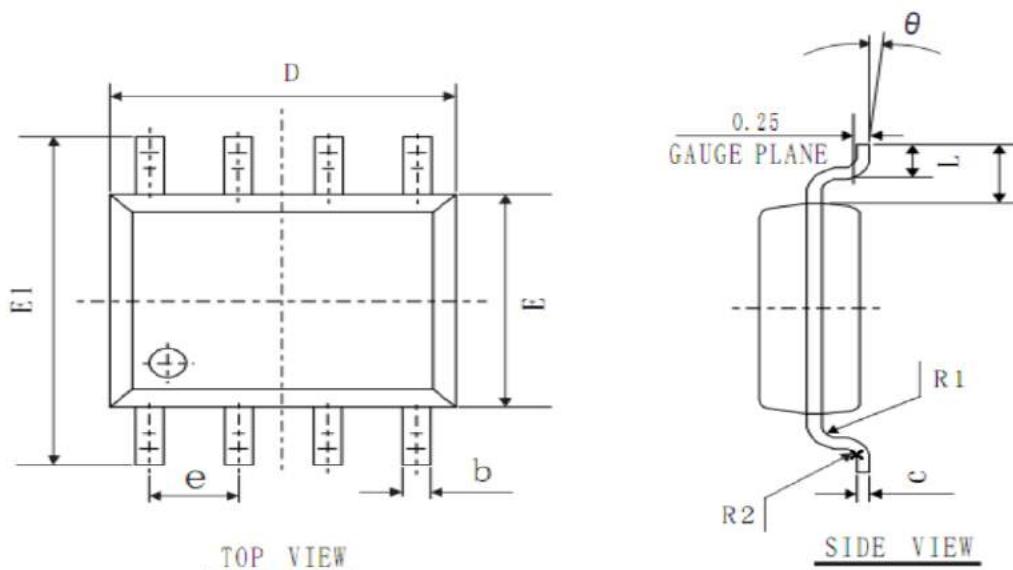


3) Switch Time Test Circuit





SOP-8 Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
θ	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		

Customer Service

Sales and Service:

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